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## (54) CIRCUIT SUBSTRATE AND MODULE

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#### (57) ABSTRACT

A circuit board 1 including: a substrate; an electrode pad on a surface of the substrate; and a projecting electrode on the electrode pad, wherein the electrode pad on which the projecting electrode is disposed is larger than the projecting electrode when viewed from above, and a coating layer covers at least a portion of an outer periphery of the electrode pad on which the projecting electrode is disposed.

